

**AMENDMENTS TO THE CLAIMS:**

*Please amend the claims as follows:*

1. (Currently amended) An electronic component comprising:  
a conductive pattern provided on an insulating substrate;  
a metal film formed by a plating method on a surface of the conductive pattern; and  
a metal oxide layer formed by oxidizing the metal film and disposed on the surface of the conductive pattern,

wherein the metal oxide layer is formed on a portion of the substrate between electrodes of the conductive pattern on the substrate.

2. (Cancelled)

3. (Previously presented) The electronic component as defined in claim 1, wherein the metal film is formed by a plating method on a surface of the substrate, where the conductive pattern is provided.

4. (Previously presented) The electronic component as defined in claim 1, wherein the substrate uses a ceramic substrate.

5. (Previously presented) The electronic component as defined in claim 1, wherein the substrate uses a glass-ceramic substrate.

6. (Previously presented) The electronic component as defined in claim 1, wherein the substrate uses an organic substrate.

7. (Previously presented) The electronic component as defined in claim 1, wherein the conductive pattern uses electrode material including at least Ag.

8. (Original) The electronic component of claim 7, wherein the electrode material includes one material selected from the group consisting of Ag, Ag – Pt, and Ag – Pd.

9. (Previously presented) The electronic component as defined in claim 1, wherein the metal oxide layer includes one material selected from the group consisting of NiO, ZnO, and CuO.

10. (Previously presented) The electronic component as defined in claim 9, wherein the metal oxide layer has a thickness ranging from 0.5 $\mu$ m to 5 $\mu$ m.

11. (Cancelled)

12. (Previously presented) The electronic component as defined in claim 1, wherein a part of the conductive pattern is exposed outward from the surface of the component.

13. (Previously presented) The electronic component as defined in claim 2, wherein a part of the conductive pattern and a part of the substrate are exposed outward.

14. (Previously presented) The electronic component as defined in claim 3, wherein a part of the conductive pattern and a part of the substrate are exposed outward from the surface of the component.

15. (Withdrawn – currently amended) A method of manufacturing an electronic component, the method comprising the steps of:

forming a conductive pattern on a surface of an insulating substrate;

forming a metal film by a plating method on a surface of the conductive pattern and on a portion of the surface of the insulating substrate; and

forming a metal oxide layer ~~on the surface of the conductive pattern~~ by oxidizing the metal film on the surface of the conductive pattern and on the portion of the surface of the insulating substrate.

16-17. (Cancelled)

18. (Withdrawn) The method as defined in one of claim 15, wherein the plating method uses an electroless plating method.

19. (Withdrawn) The method as defined in claim 15 wherein the oxidizing is done by a heat treatment.

20. (Withdrawn) The method as defined in claim 19, wherein the heat treatment is carried out at a temperature not higher than a melting point of the conductive pattern.

21. (Withdrawn – currently amended) ~~[[A]] The method of manufacturing an electronic component according to claim 15, wherein the method comprising the steps of:~~

~~forming a conductive pattern on an insulating substrate;~~

~~forming the metal film is a nickel film, and by a plating method at least on a surface of the conductive pattern;~~

~~said step of forming the metal oxide layer comprises forming a nickel oxide layer as [[a]] the metal oxide layer at least on the surface of the conductive pattern by providing the nickel film with an oxidation heat treatment at a temperature between 850°C and a melting point of electrode material forming the conductive pattern.~~